# HFW1V22xxH High current flat wire inductor



## **Product features**

- · Flat wire construction, high current capability
- 22.3 mm x 22 mm surface mount package in 10.2, 10.8, 12.5 and 14.5 mm height
- Third mounting pad enhances stability and board adhesion
- · Inductance range: 4.7 μH to 20 μH
- Current range: 14.3 A to 28 A
- · 200 Vdc isolation voltage (winding to core)
- · Termination finish: tin
- Ferrite core material
- Moisture Sensitivity Level (MSL) 1

#### Applications

- Computing (POL/VRMs)
- · Distributed power architectures
- Servers and workstations
- · LAN / WAN applications
- · Game consoles
- Industrial IoT equipment
- Motion controls
- Battery backup
- LED lighting
- Renewable energy product
- Solar/wind generators, inverters, charger controllers
- · Medical equipment, displays

# Environmental compliance and general specifications

- Storage temperature range (Component): -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (ambient plus self-temperature rise)





## **Product specifications**

Part number⁴	OCL¹ (μH) ± 10% (Pin 1-2)	I <sub>rms</sub> ² (A) typical	l <sub>sat</sub> <sup>3</sup> (A) (Pin 1-2)	DCR (mΩ) maximum (Pin 1-2) @ +25 °C	SRF (MHz) (Pin 1-2)
HFW1V2210H4R7K	4.7	28	22.0	2.4	17
HFW1V2210H6R8K	6.8	26.5	19.0	2.9	15
HFW1V2211H8R2K	8.2	24	18.5	3.4	15
HFW1V2213H100K	10	22	21.0	3.9	14
HFW1V2213H150K	15	22	15.3	3.9	12
HFW1V2215H200K	20	19	14.3	6.4	9.0

1. Open circuit inductance (OCL) Test parameters: 100 kHz, 1.0 V ...., 0.0 Adc, +25 °C

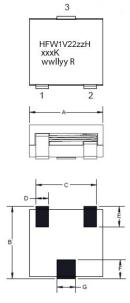
3. I<sub>sat</sub>: Peak current for approximately 20% rolloff @ +25 °C

2. Ims. DC current for an approximate temperature rise of 40 °C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed +125 °C under worst case operating conditions verified in the end application.

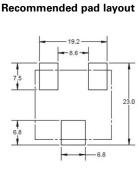
4. Part Number Definition: HFWxVxxxxHxxxK

HFW1V2210H = Product code and size,

xxx= inductance value in uH , R = decimal point, if no R is present then third digit equals number of zeros, K = tolerance 10%



# Mechanical parameters, schematic, pad layout (mm)







Part number	А	В	С	D	E	F	G	н
HFW1V2210H4R7K	22.3 maximum	22 maximum	17.8 ± 0.5	$3.8 \pm 0.3$	6.0 ± 0.5	$5.5 \pm 0.3$	5.5 ± 0.3	10.2
HFW1V2210H6R8K	22.3 maximum	22 maximum	17.8 ± 0.5	3.8 ± 0.3	6.0 ± 0.5	5.5 ± 0.3	5.5 ± 0.3	10.2
HFW1V2211H8R2K	22.3 maximum	22 maximum	17.8 ± 0.5	3.8 ± 0.3	6.0 ± 0.5	5.5 ± 0.3	5.5 ± 0.3	10.8
HFW1V2213H100K	22.3 maximum	22 maximum	17.8 ± 0.5	3.8 ± 0.3	6.0 ± 0.5	5.5 ± 0.3	5.5 ± 0.3	12.5
HFW1V2213H150K	22.3 maximum	22 maximum	17.8 ± 0.5	3.8 ± 0.3	6.0 ± 0.5	5.5 ± 0.3	5.5 ± 0.3	12.5
HFW1V2215H200K	22.3 maximum	22 maximum	17.8 ± 0.5	3.8 ± 0.3	6.0 ± 0.5	5.5 ± 0.3	5.5 ± 0.3	14.5

Part marking: HFW1V22zzH: zz= 10, 11, 13 or 15

xxxK= inductance value in uH, R= decimal point, If no R is present, third character equals numbers of zeros, K= tolerance ±10% wwllyy R= lot code

0.15

All soldering surfaces to be coplanar within 0.15 millimeters

Pad layout tolerances are  $\pm 0.1$  millimeters unless stated otherwise

Pin 3 is for mounting purposes. No connection.

Traces or vias underneath the inductor is not recommended

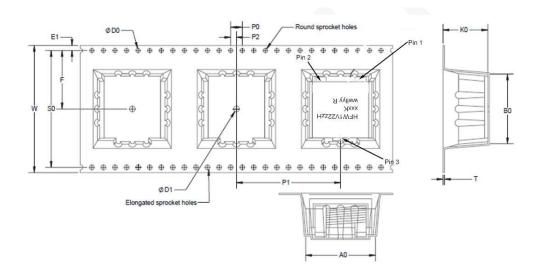
# HFW1V22xxH High current flat wire inductor

# Packaging information (mm)

Drawing not to scale

Supplied in tape and reel packaging in a 13" diameter reel (EIA-481 compliant)

HFW1V2210H4R7K	90 part per reel
HFW1V2210H6R8K	90 parts per reel
HFW1V2211H8R2K	90 parts per reel
HFW1V2213H100K	80 parts per reel
HFW1V2213H150K	80 parts per reel
HFW1V2215H200K	70 parts per reel

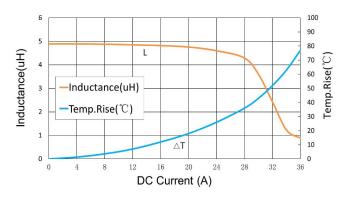


Dimension	HFW1V2210	HFW1V2211	HFW1V2213	HFW1V2215
W ± 0.30	44.0	44.0	44.0	44.0
F ± 0.10	20.2	20.2	20.2	20.2
E1 ± 0.10	1.75	1.75	1.75	1.75
S0 ± 0.10	40.4	40.4	40.4	40.4
P0 ± 0.10	4.0	4.0	4.0	4.0
P1 ± 0.10	32.0	32.0	36.0	36.0
P2 ± 0.10	2.0	2.0	2.0	2.0
D0 + 0.10/-0	1.5	1.5	1.5	1.5
D1 + 0.10/-0	2.0	2.0	2.0	2.0
A0 ± 0.15	22.6	22.6	22.6	22.6
B0 ± 0.15	22.6	22.6	22.6	22.6
K0 ± 0.15	11.2	11.8	13.8	15.5
T ± 0.05	0.5	0.5	0.5	0.5

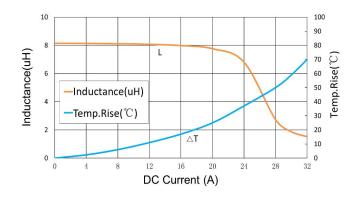
Technical Data **ELX1331** Effective June 2023

#### Inductance characteristics (+25 °C)

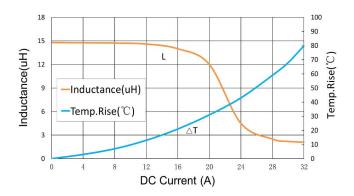
#### HFW1V2210H4R7K



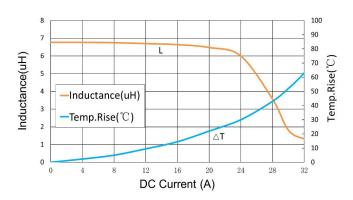
## HFW1V2211H8R2K

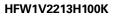


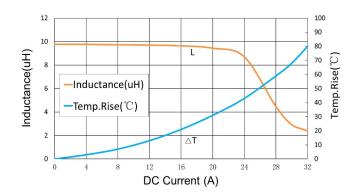
#### HFW1V2213H150K



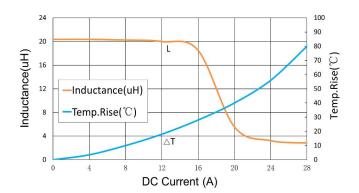
HFW1V2210H6R8K







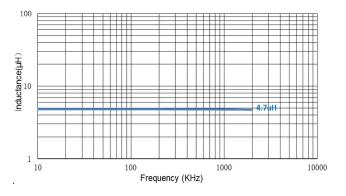
#### HFW1V2215H200K



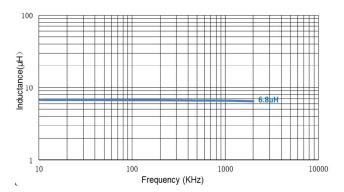
Technical Data **ELX1331** Effective June 2023

# Inductance vs. frequency curve

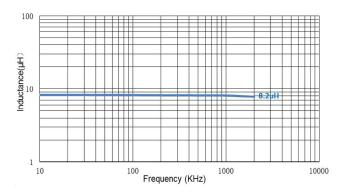
# HFW1V2210H4R7K



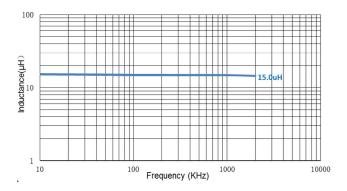
HFW1V2210H6R8K



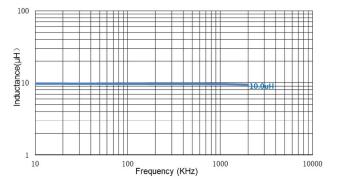
#### HFW1V2211H8R2K



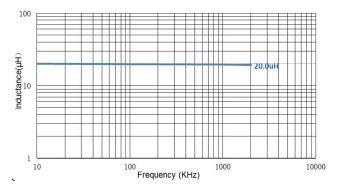
#### HFW1V2213H150K



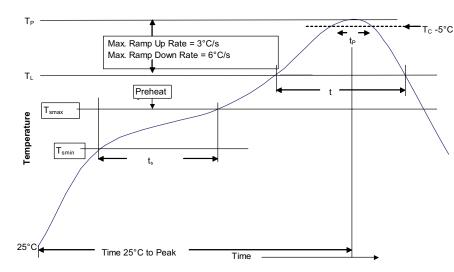
#### HFW1V2213H100K



# HFW1V2215H200K



#### Solder reflow profile



Package thickness	Volume mm3 <350	Volume mm3 ≥350
<2.5 mm	235 °C	220 °C
≥2.5 mm	220 °C	220 °C

#### Table 2 - Lead (Pb) free solder (T<sub>c</sub>)

Table 1 - Standard SnPb solder (T<sub>c</sub>)

\	Package thickness	Volume mm <sup>3</sup> <350	Volume mm <sup>3</sup> 350 - 2000	Volume mm <sup>3</sup> >2000
	<1.6 mm	260 °C	260 °C	260 °C
	1.6 – 2.5 mm	260 °C	250 °C	245 °C
	>2.5 mm	250 °C	245 °C	245 °C

#### **Reference J-STD-020**

Profile feature	Standard SnPb solder	Lead (Pb) free solder 150 °C	
Preheat and soak • Temperature min. (T <sub>smin</sub> )	100 °C		
• Temperature max. (T <sub>smax</sub> )	150 °C	200 °C	
• Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	60-120 seconds	60-120 seconds	
Ramp up rate T <sub>L</sub> to T <sub>p</sub>	3 °C/ second max.	3 °C/ second max.	
Liquidous temperature (TL) Time (tL) maintained above $T_{\!L}$	183 °C 60-150 seconds	217 °C 60-150 seconds	
Peak package body temperature (Tp)*	Table 1	Table 2	
Time $(t_p)^*$ within 5 °C of the specified classification temperature $(T_c)$	20 seconds*	30 seconds*	
Ramp-down rate (Tp to TL)	6 °C/ second max.	6 °C/ second max.	
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.	

 $^{\ast}$  Tolerance for peak profile temperature (T  $_{\rm D})$  is defined as a supplier minimum and a user maximum.

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